# Recent Advances in Additive and Intelligent Manufacturing

Guest Editor:

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Deadline for manuscript
submissions:
**closed (5 August 2022)**

## Message from the Guest Editor

Dear Colleagues,

This Special Issue of MDPI's journal *Micromachines* aims to provide a platform for researchers to showcase findings when applying additive manufacturing and AI/machine learning technologies in miniaturized/micro/nano-scaled structures, materials, devices, and systems. Original research articles and reviews are invited for this SI.

Topics of interest include, but are not limited to:

- 3D-printed miniaturized/micro/nano devices and structures.
- Applications of additive manufacturing.
- Micro/nano additive manufacturing.
- Novel materials and inks.
- Mass customization and production using AM.
- Topology optimization and generative design.
- Design of miniaturized/micro/nano devices for additive manufacturing.
- Nature and bio-inspired design.
- Digital twins and cyber-physical systems for additive manufacturing.
- AI/machine learning in additive manufacturing.
- Process planning and optimization, including hardware and software.
- Development, modeling, and simulation of AM processes.

Dr. Huachao Mao
*Guest Editor*

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**Special** Issue

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## Message from the Editor-in-Chief

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